

KYOCERA KE-300K

Epoxy; Epoxide

KYOCERA Chemical Corporation

Message:

Achieved Fast Cure for In-Line Process as well as Excellent Fillings and Applicable from Insertion Type to Surface Mount Type.

Strong Points

Achieve Good and Necessary Filling in KE-520Series to Apply to Ultra Small Packages.

JEDEC level 1 is Possible in Ultra Small Packages.

Good Adhesion Strength Even after High Temperature Reflow Soldering Process.

Fast Cure Enabling High Productive In-Line Auto Process.

Excellent moldability and show improvement in moldability yield.

Application

Surface Mount Device

TO-92 Type (Insertion Type)

Ultrasmall PKG

General Information		
Features	Fast Cure	
	Good Adhesion	
	Good Moldability	
Uses	Electrical/Electronic Applications	
Physical	Nominal Value	Unit
Specific Gravity	1.80	g/cm ³
Spiral Flow	100	cm
Thermal	Nominal Value	Unit
Glass Transition Temperature	180	°C
CLTE - Flow		
-- 1	1.8E-5	cm/cm/°C
-- 2	6.7E-5	cm/cm/°C
Uncured Properties	Nominal Value	Unit
Gel Time	0.45	min
NOTE		
1.	Alpha 1	
2.	Alpha 2	

The information and data on this page are provided by manufacturers and document providers. SHANGHAI SUSHENG assumes no legal liability. It is strongly recommended to verify all technical data with material suppliers before final material selection. All rights belong to the original authors. If any infringement occurs, please contact us immediately.

Recommended distributors for this material

Susheng Import & Export Trading Co.,Ltd.

Tel: +86 21 5895 8519

Phone: +86 13424755533

Email: sales@su-jiao.com

No. 215, Lianhe North Road, Fengxian District, Shanghai, China

